



PATENT
TESSERA 3.0-078 DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of :
Fjelstad et al. :
 : Group Art Unit: 2814
Application No. 09/020,647 :
 : Examiner: D. Graybill
Filed: February 9, 1998 :
 : Date: October 1, 2001
For: Methods of Making Compliant :
Semiconductor Chip Packages :
(As Amended) X
Box CPA
Commissioner for Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Preliminary to initiation of continued prosecution of the
above-identified application, please amend the application as
follows:

IN THE TITLE

Please amend the title of the above-identified application
to: --Methods of Making Compliant Semiconductor Chip Packages

IN THE CLAIMS

Please cancel claims 1-11 and 21-34.

Insert new claims 35-57 as follows:

35. (New) A method of making a compliant semiconductor
chip package comprising:

providing a semiconductor chip having a contact bearing
surface including a central region bounded by a peripheral
region, wherein the peripheral region of said contact bearing
surface has chip contacts;

EXPRESS MAIL LABEL NUMBER: EL 804525924 US

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